



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HBZG*Z72Q81U	A	BOUSKOURA B/E	2015-06-18
Amount	UoM	Unit type	ST ECOPACK Grade	
98	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.2, 3.7, 2.37	2	J BEND	
Comment	Package: SMB CLIP (SOD 6), MD valid for CP:STP55L60U.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HB2G*Z72Q81U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	3.511	mg	supplier	die	Silicon (Si)	7440-21-3		3.421	mg	974366	34908
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	3133	112
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	3987	143
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	570	20
				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1424	51
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	6551	235
Leadframe	Copper & its alloys	41.514	mg	supplier	polymer die coating	Durimide	proprietary		0.035	mg	9969	357
				supplier	alloy	Copper (Cu)	7440-50-8		40.623	mg	978537	414520
				supplier	alloy	Iron (Fe)	7439-89-6		0.041	mg	988	418
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	289	122
				supplier	metallization	Nickel (Ni)	7440-02-0		0.833	mg	20066	8500
Soft solder	Solder	3.362	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.144	mg	935158	32082
				supplier	solder	Tin (Sn)	7440-31-5		0.168	mg	49970	1714
				supplier	solder	Silver (Ag)	7440-22-4		0.050	mg	14872	510
Encapsulation	Other Organic Materials	30.472	mg	supplier	mold compound	Silica, vitreous	60676-86-0		23.159	mg	760009	236316
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.108	mg	101995	31714
				supplier	mold compound	Phenol resin	9003-35-4		1.828	mg	59989	18653
				supplier	mold compound	Others	Proprietary		1.524	mg	50013	15551
				supplier	mold compound	Metal hydroxide	Proprietary		0.609	mg	19986	6214
connections coating	Solder	0.811	mg	supplier	mold compound	Carbon black	1333-86-4		0.244	mg	8007	2490
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276
Clip	Copper & its alloys	18.330	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.330	mg	1000000	187041